

ABSTRACT

In a manufacturing method for an interposer, a seed layer is formed at an opening portion in a through hole on back surface side of a substrate, an electrode layer for electroplated coating is formed based on the seed layer, and an electroplated coating layer is formed to fill the through hole from the electrode layer for electroplated coating layer to a front surface side. As a result, a manufacturing method for an interposer is provided in which the manufacturing process is simple and the void is not generated inside of the through hole.